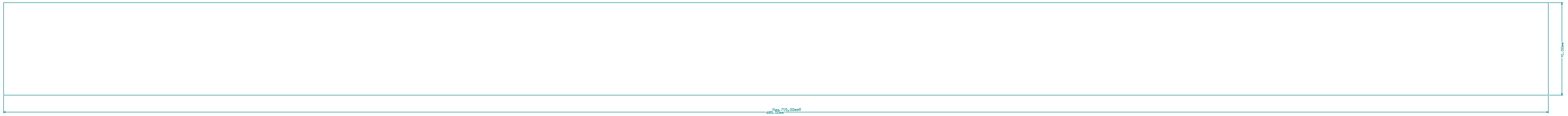

41.00mm
Max.715,00mm!!!
685.00mm

POH MB v1.3.1 - 0.5mm, 5-layer Board

Material Selection

Halogen-free FR-4
Permittivity @ 100MHz:
Permittivity @ 1GHz:
Loss Tangent @ 100MHz:
Loss Tangent @ 1GHz:
Lead Free Assembly Compatible

Solder resist colour: green
Silkscreen print colour: white

Surface Finish

On top and bottom layer surfaces:
electroless nickel immersion gold

Holes / Drilling

Drill files contain finished hole diameters
Drilling layer pairs: 1-5

Board Outline

Contour routed with break-away tabs

Element Counts
(for reference only)

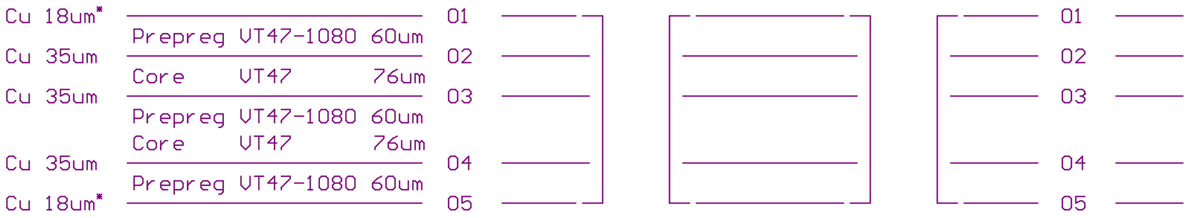
Components:	98
Nets:	134
Pads:	1012
Tracks:	4524
Polygons:	0
Holes:	734
Vias:	654

Non-standard Tolerances

Holes sized 0.2mm may be plugged by plating. These are all vias.
For them we do not care the finished hole sizes.

Board Layer Stack

Drill Layer-Pairs



*35um final after plating

Total Laminated Thickness: 0.5mm +/- 0.05mm !

Layer Name	Gerber
Top Paste Mask	.gtp
Top Overlay	.gto
Top Solder Mask	.gts
Top Layer	.gtl
Plane 1 (GND)	.gp1
Mid Layer 1	.g1
Plane 2 (PWR)	.gp2
Bottom Layer	.gbl
Bottom Solder Mask	.gbs
Board Outline	.gm1

Controlled Impedance Reference

Diff. trace width/space on middle layer 1 (stripline) 60 ohms +/- 10% : 0.15/0.1mm
Diff. trace width/space on top and bottom layer (microstrip) 60 ohms +/- 10% : 0.175/0.1mm